WHAT IS CLAIMED IS:

1. An electroplating system comprising:

a plating chamber configured to deposit metal material onto substrates positioned in the plating chamber, the plating chamber comprising a rotor and a vessel;

a weir thief electrode disposed in the vessel; and

at least one of baffle positioned in the plating chamber, the at least one baffle defining a plurality of slots, the at least one baffle configured to prevent fluid from splashing the rotor or the plating chamber during operation of the plating chamber, wherein each slot of the at least one baffle is disposed radially outward of the weir thief electrode, wherein each slot of the at least one baffle extends vertically through at least a thickness of a respective baffle.

2. The electroplating system of claim 1, wherein the at least one baffle is positioned at a top of the vessel at least partially above a fluid line of the fluid.

3. The electroplating system of claim 1, wherein the at least one baffle further comprises a mounting tab defining at least one mounting hole, wherein the mounting tab extends within at least one slot of the plurality of slots, the at least one mounting hole sized to receive a mounting screw.

4. The electroplating system of claim 1, wherein the at least one baffle further comprises a mounting tab defining at least one mounting hole, wherein the mounting tab is positioned external to the plurality of slots, the at least one mounting hole sized to receive a mounting screw.

5. The electroplating system of claim 1, wherein the at least one baffle is positioned horizontally adjacent to a weir thief electrode assembly and vertically adjacent to the rotor and a paddle, the paddle positioned on the weir thief electrode assembly and configured to move in at least one direction, and wherein the at least one baffle prevents motion of the fluid in at least one direction by obstructing fluid movement using the plurality of slots.

6. The electroplating system of claim 1, wherein a height of the at least one baffle is greater than or about 15% of a length of the at least one baffle.

7. The electroplating system of claim 1, wherein a mesh is positioned in each slot of the plurality of slots.

8. An electroplating system comprising:

a vessel assembly for holding an electrolyte;

a weir thief electrode assembly in the vessel assembly; and

at least one baffle disposed in the vessel assembly, the at least one baffle defining a plurality of slots, the at least one baffle configured to prevent fluid from splashing a rotor or a plating chamber during operation of the electroplating system, wherein each slot of the at least one baffle is disposed radially outward of the weir thief electrode, and wherein each slot of the at least one baffle extends vertically through at least a thickness of a respective baffle.

9. The electroplating system of claim 8, wherein the at least one baffle is positioned at a top of the vessel assembly at least partially above a fluid line of the electrolyte.

10. The electroplating system of claim 8, wherein the at least one baffle further comprises a mounting tab defining at least one mounting hole, wherein the mounting tab extends within at least one slot of the plurality of slots, the at least one mounting hole configured to facilitate attachment of the at least one baffle to the weir thief electrode.

11. The electroplating system of claim 8, wherein the at least one baffle further comprises a mounting tab defining at least one mounting hole, wherein the mounting tab is positioned external to the plurality of slots, the at least one mounting hole sized to receive a mounting screw.

12. The electroplating system of claim 8, wherein a height of the at least one baffle is greater than or about 15% of a length of the at least one baffle.

13. The electroplating system of claim 8, wherein a mesh is positioned in each slot of the plurality of slots.

14. The electroplating system of claim 8 wherein the at least one baffle further comprises a mounting tab defining at least one mounting hole, wherein the mounting tab extends within at least one slot of the plurality of slots, the at least one mounting hole sized to receive a mounting screw.

15. The electroplating system of claim 11, wherein the mounting tab is a flange positioned on the at least one baffle for coupling the at least one baffle to the plating chamber.

16. The electroplating system of claim 8, wherein adjacent slots of the plurality of slts are separated by a dividing member that extends along the thickness of the respective baffle.

17. The electroplating system of claim 8, wherein each slot of the plurality of slots is characterized by a width of less than or about 25% of a length of the at least one baffle.